

PATENT NUMBER and
ISSUE DATE

U.S. UTILITY Patent Application

APPL. NUM	FILING DATE	CLASS	SUBCLASS	GAU
10038806	01/02/2002	257		2811

EXAMINER

**APPLICANTS: Takeuchi Timothy;

**CONTINUING DATA VERIFIED:

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** FOREIGN APPLICATIONS VERIFIED:

PG-PUB DO NOT PUBLISH

RESCIND

ATTORNEY DOCKET NO.

Foreign priority claimed

yes no

35 USC 119 conditions met

yes no

Verified and Acknowledged Examiner's initials

42P13557

TITLE : Semiconductor package with integrated heat spreader attached to a thermally conductive substrate core

U.S. DEPT. OF COMM./PAT. & TM-PTO-436L(Rev. 12-94)

NOTICE OF ALLOWANCE MAILED

ISSUE FEE

Amount Due

Date Paid

Assistant Examiner

Primary Examiner

CLAIMS ALLOWED

Total Claims

Print Claims for
0.0

DRAWING

Sheets Draw.

Fig.s Draw.

Print Fig.

Application Examiner

TERMINAL
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